

S50 5	45	floating adj catalyst	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/27 22:04
S50 6	6	floating adj catalyst and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/27 22:07
S50 7	546	surface adj catalyst and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/27 22:08
S50 8	44	surface adj catalyst and barrier and electroless	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/27 22:08
S50 9	397	438/69	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:56
S51 0	258	438/72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:56
S51 1	2307	438/618	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:56
S51 2	3229	438/622	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:56

S51 3	754	438/625	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:56
S51 4	1	438/636-637	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:56
S51 5	704	438/636	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:57
S51 6	3608	438/637	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:57
S51 7	416	438/642	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:57
S51 8	832	438/652	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:57
S51 9	1614	438/653	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:57
S52 0	462	438/654	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:57

S52 1	872	438/669	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:57
S52 2	1424	438/672	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:58
S52 3	1174	438/675	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:58
S52 4	947	438/688	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:58
S52 5	372	438/737	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:58
S52 6	1019	438/738	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:58
S52 7	221	438/749	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 11:59
S52 8	244	438/751	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:00
S52 9	0	("metaladjline").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/04/06 12:01

S61 8	0	S523 and S533 and S538 and mask adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:37
S61 9	2	S524 and S533 and S538 and mask adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:37
S62 0	1	S525 and S533 and S538 and mask adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:37
S62 1	2	S526 and S533 and S538 and mask adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:37
S62 2	0	S527 and S533 and S538 and mask adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:37
S62 3	0	S528 and S533 and S538 and mask adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:39
S62 4	0	S533 and S537 and S539 and S543 and mask adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:40
S62 5	0	S533 and S537 and S539 and S543 and resist adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 12:41

S62 6	4	S533 and S543 and resist adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 14:26
S62 7	13	(metal adj line or metal adj layer or buried adj layer or aluminum adj layer or conductive adj layer or conductive adj line) and (adhesive adj layer or titanium adj layer or titanium adj nitride adj layer) and (anti-reflective or anti adj reflective adj layer) and (photoresist or mask) and (etching adj gas)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 13:00

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(metal adj line or metal adj layer or buried adj layer or aluminum adj layer or conductive adj layer or conductive adj line) and (adhesive adj layer or titanium adj layer or titanium adj nitride adj layer) and (anti-reflective or anti adj reflective adj layer) and (photoresist or mask) and (etching adj gas) and "Al.sub.2Cu"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 16:09
L2	1	"NF.sub.2" and "C.sub.3F.sub.8"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 16:07
L3	190	"N.sub.2" and "C.sub.3F.sub.8"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 16:08
L4	2	"N.sub.2" and "C.sub.3F.sub.8" and wiring adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 16:08
L5	13	(wiring adj line or metal adj layer or buried adj layer or aluminum adj layer or conductive adj layer or conductive adj line) and (adhesive adj layer or titanium adj layer or titanium adj nitride adj layer) and (anti-reflective or anti adj reflective adj layer) and (photoresist or mask) and (etching adj gas)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/06 16:10